

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	3536	"257"/\$.ccls. and (board carrier substrate) and (dummy adj (spacer bump ball) spacer) and (tape adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 16:45
L3	766	"257"/\$.ccls. and (board carrier substrate) same (dummy adj (spacer bump ball) spacer) same (chip die ic) and (tape adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 16:45
L4	752	"257"/\$.ccls. and (board carrier substrate) same (dummy adj (spacer bump ball) spacer) same (chip die ic) and (tape adhesive) and (contact pad electrode)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 16:46
L5	473	"257"/\$.ccls. and (board carrier substrate) same (contact pad electrode) same (dummy adj (spacer bump ball) spacer) same (chip die ic) and (tape adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 16:56
L6	32	"257"/\$.ccls. and (board carrier substrate) same (contact pad electrode) same (dummy adj (spacer bump ball)) same (chip die ic) and (tape adhesive resin epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 16:58
L7	105	"257"/\$.ccls. and (board carrier substrate) and (contact pad electrode) and (dummy adj (spacer bump ball)) and (chip die ic) and (tape adhesive resin epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 17:10
L8	37	"438"/\$.ccls. and (board carrier substrate) and (contact pad electrode) and (dummy adj (spacer bump ball)) and (chip die ic) and (tape adhesive resin epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 17:10
L9	8	"361"/\$.ccls. and (board carrier substrate) and (contact pad electrode) and (dummy adj (spacer bump ball)) and (chip die ic) and (tape adhesive resin epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 17:10
L10	433	"257"/\$.ccls. and (board carrier substrate) and (contact pad electrode) and spacer with (solder bump ball) and (chip die ic) and (tape adhesive resin epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 17:43

L14	177	"438"/\$.ccls. and (board carrier substrate) and (contact pad electrode) and spacer with (solder bump ball) and (chip die ic) and (tape adhesive resin epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 17:47
L15	111	"361"/\$.ccls. and (board carrier substrate) and (contact pad electrode) and spacer with (solder bump ball) and (chip die ic) and (tape adhesive resin epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 17:49
L16	9	"156"/\$.ccls. and (board carrier substrate) and (contact pad electrode) and spacer with (solder bump ball) and (chip die ic) and (tape adhesive resin epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 17:50
L17	63	"228"/\$.ccls. and (board carrier substrate) and (contact pad electrode) and spacer with (solder bump ball) and (chip die ic) and (tape adhesive resin epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 17:50